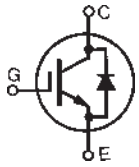
IXYS

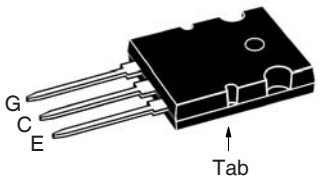
HiPerFAST™ High Speed IGBT C2-Class w/ Diode

IXGK50N60C2D1
IXGX50N60C2D1

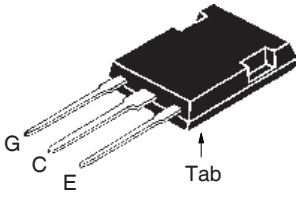
V_{CES} = 600V
I_{C110} = 50A
$V_{CE(sat)}$ ≤ 2.7V
$t_{fi(typ)}$ = 48ns



TO-264 (IXGK)



PLUS247 (IXGX)



G = Gate E = Emitter
C = Collector Tab = Collector

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C (Limited by Leads)	75	A
I_{C110}	T_C = 110°C	50	A
I_{F110}	T_C = 110°C	48	A
I_{CM}	T_C = 25°C, 1ms	300	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 10Ω Clamped Inductive Load	I_{CM} = 100 $V_{CE} \le V_{CES}$	A
P_C	T_C = 25°C	480	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
M_d	Mounting Torque (TO-264)	1.13 / 10	Nm/lb.in
F_C	Mounting Force (PLUS247)	20..120 / 4.5..27	N/lb
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6mm (0.062 in.) from Case for 10s	260	°C
Weight	TO-264	10	g
	PLUS247	6	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	3.0		5.5	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V			650	μA
	T_J = 125°C			5	mA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 40A, V_{GE} = 15V, Note 1			2.7	V
	T_J = 125°C		1.8		V

Features

- Very High Frequency IGBT
- Square RBSOA
- Anti-Parallel Ultra Fast Diode
- High Current Handling Capability

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- PFC Circuits
- AC Motor Drives
- DC Servo & Robot Drives
- DC Choppers

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 40A, V_{CE} = 10V, Note 1	40	51		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		3700		pF
C_{oes}			290		pF
C_{res}			50		pF
$Q_{g(on)}$	I_C = 40A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		138		nC
Q_{ge}			25		nC
Q_{gc}			40		nC
$t_{d(on)}$	**Inductive load, T_J = 25°C**		18		ns
t_{ri}	I_C = 40A, V_{GE} = 15V		25		ns
$t_{d(off)}$	V_{CE} = 0.8 • V_{CES}, R_G = 2Ω		115	150	ns
t_{fi}	Note 2		48		ns
E_{off}			0.38	0.70	mJ
$t_{d(on)}$	**Inductive load, T_J = 125°C**		18		ns
t_{ri}	I_C = 40A, V_{GE} = 15V		25		ns
E_{on}	V_{CE} = 0.8 • V_{CES}, R_G = 2Ω		1.4		mJ
$t_{d(off)}$	Note 2		170		ns
t_{fi}			60		ns
E_{off}			0.74		mJ
R_{thJC}				0.31	°C/W
R_{thCS}			0.15		°C/W

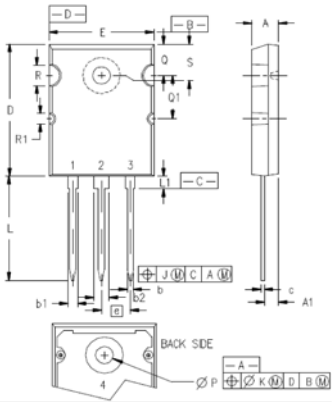
Reverse Diode (FRED)

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
V_F	I_F = 60A, V_{GE} = 0V, Note 1			2.1	V
	T_J = 150°C			1.4	V
I_{RM}	I_F = 60A, V_{GE} = 0V, -di_F/dt = 100A/μs T_J = 100°C V_R = 100 V			8.3	A
t_{rr}	I_F = 1A, -di/dt = 200A/μs, V_R = 30V		35		ns
R_{thJC}				0.65	°C/W

Notes:

1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

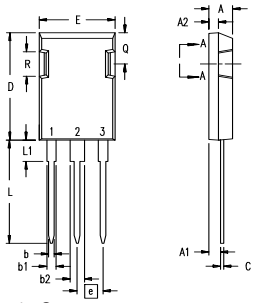
TO-264 Outline



Terminals: 1 = Gate
2,4 = Collector
3 = Emitter

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215BSC		5.46 BSC	
J	.000	.010	0.00	0.25
K	.000	.010	0.00	0.25
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
ØP	.122	.138	3.10	3.51
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
ØR	.155	.187	3.94	4.75
ØR1	.085	.093	2.16	2.36
S	.243	.253	6.17	6.43

PLUS247™ Outline



Terminals: 1 - Gate
2 - Collector
3 - Emitter

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.83	5.21	.190	.205
A_1	2.29	2.54	.090	.100
A_2	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b_1	1.91	2.13	.075	.084
b_2	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	0.244
R	4.32	4.83	.170	.190

Fig. 1. Output Characteristics @ T_J = 25ºC

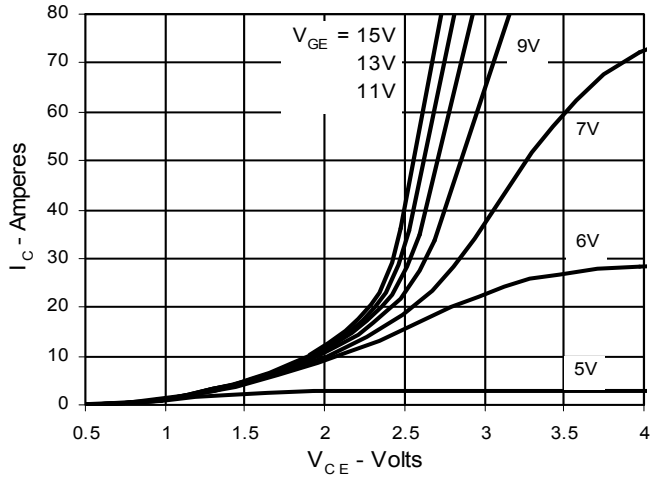


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

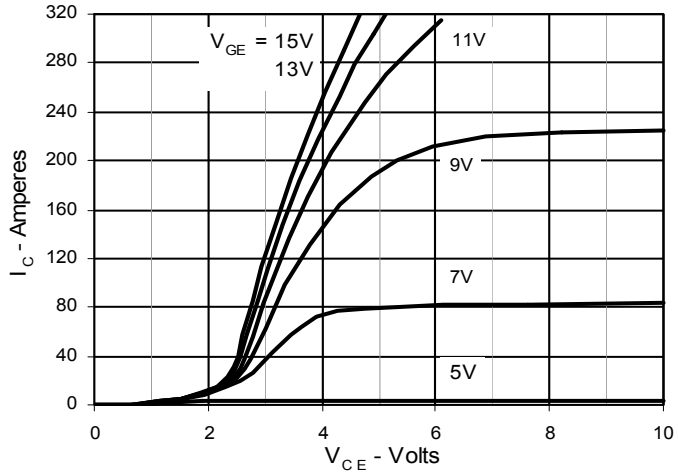


Fig. 3. Output Characteristics @ T_J = 125ºC

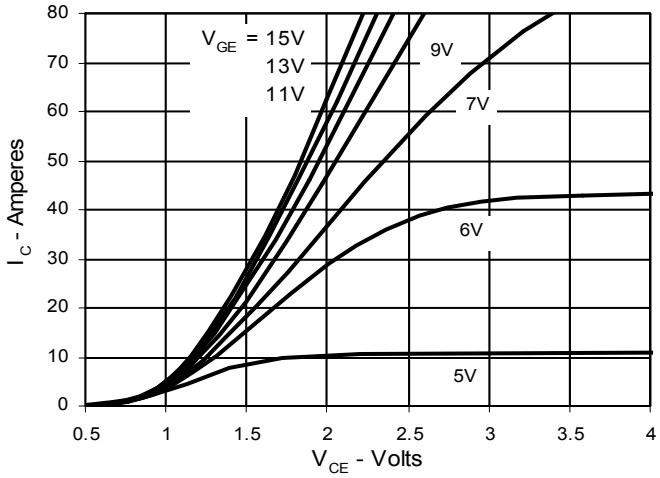


Fig. 4. Dependence of $V_{CE(sat)}$ on Temperature

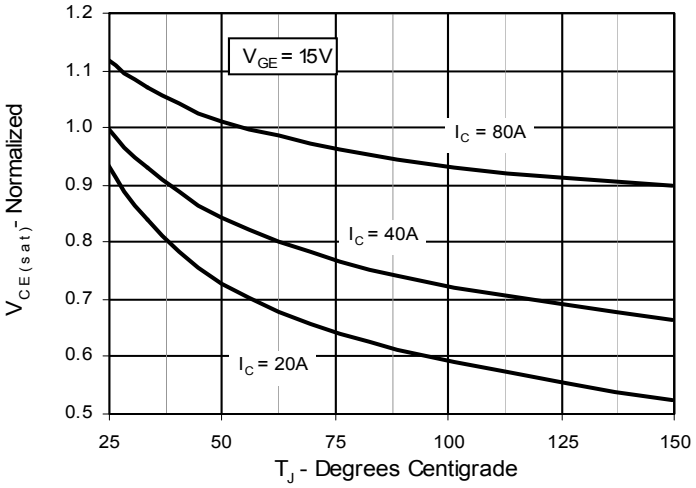


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter voltage

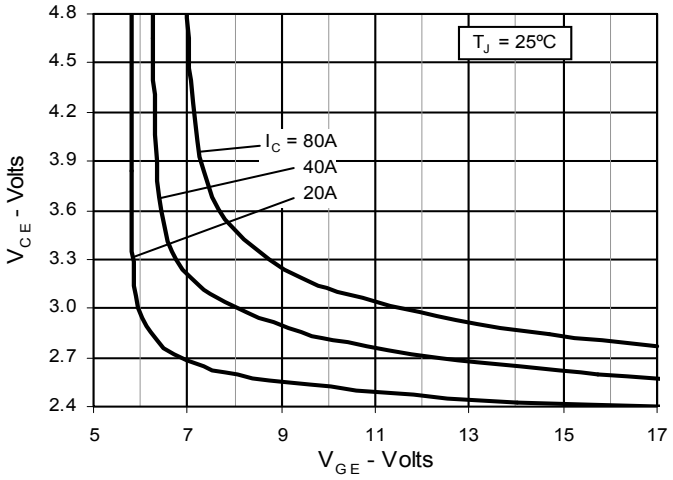


Fig. 6. Input Admittance

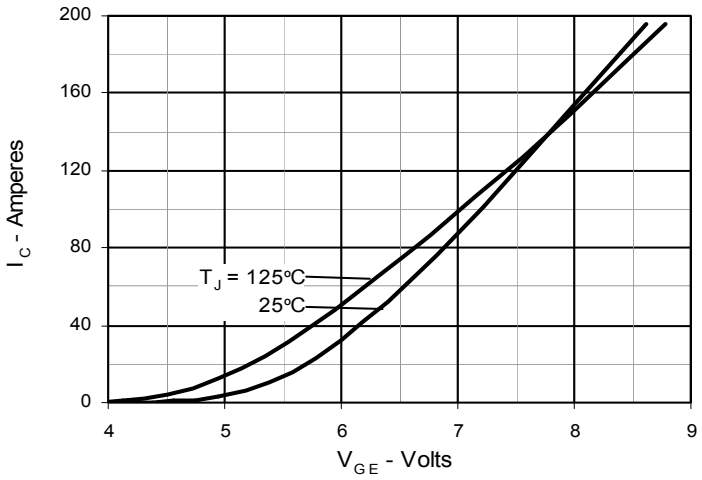


Fig. 7. Transconductance

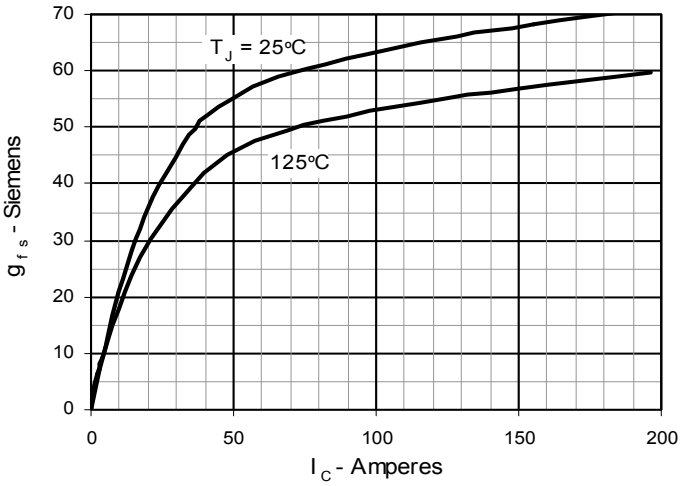


Fig. 8. Dependence of Turn-Off Energy on R_G

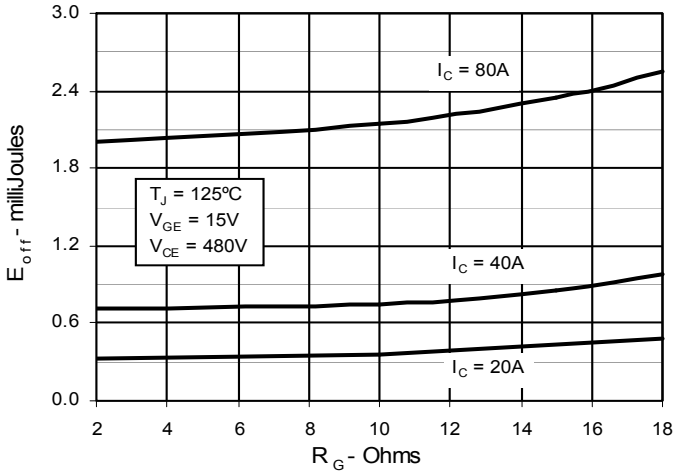


Fig. 9. Dependence of Turn-Off Energy on I_c

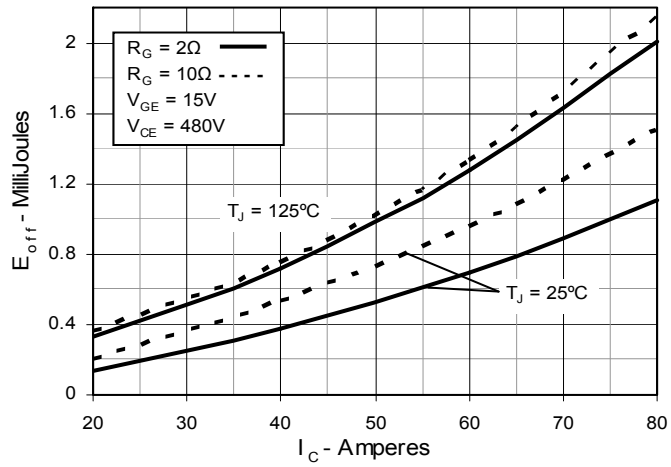


Fig. 10. Dependence of Turn-Off Energy on Temperature

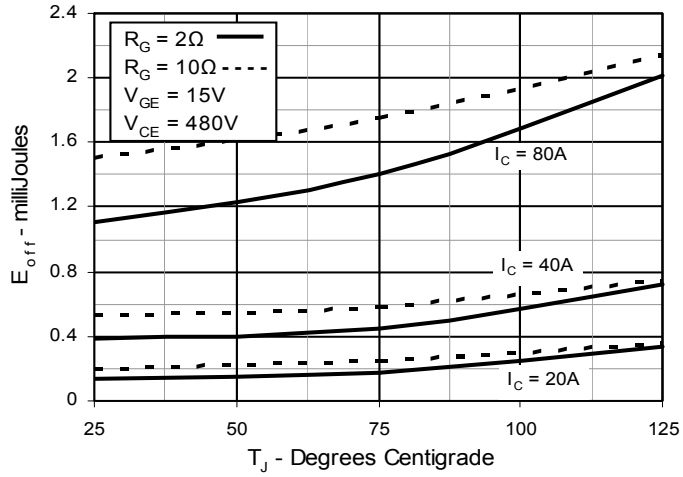


Fig. 11. Dependence of Turn-Off Switching Time on R_G

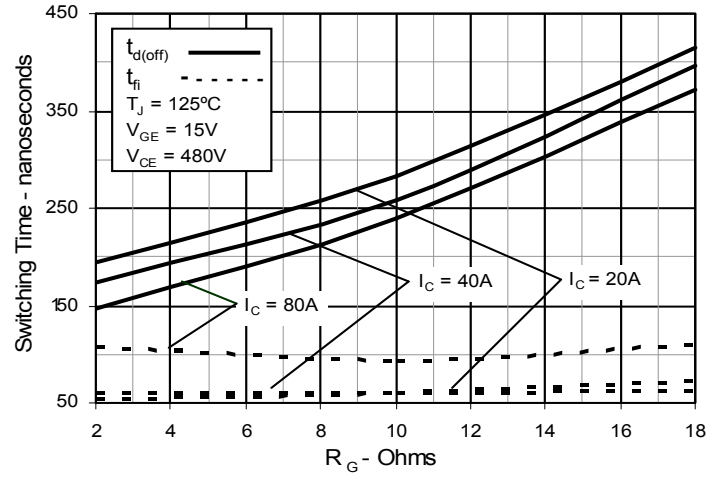


Fig. 12. Dependence of Turn-Off Switching Time on I_c

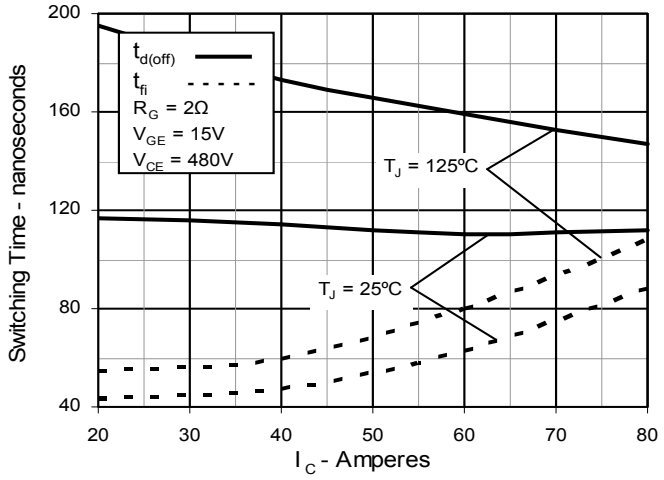


Fig. 13. Dependence of Turn-Off Switching Time on Temperature

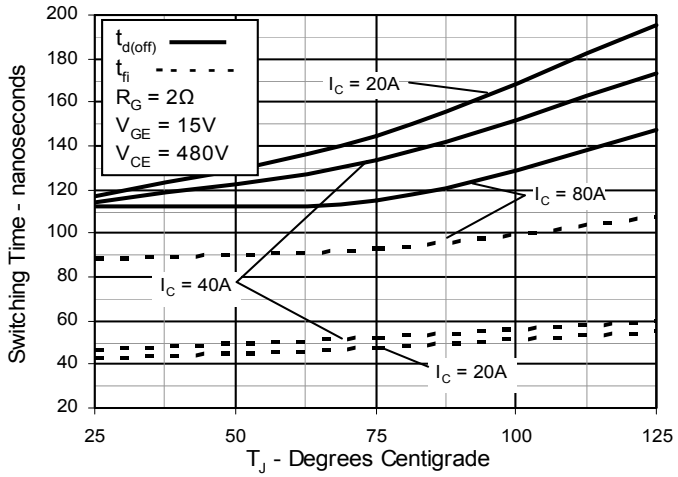


Fig. 14. Reverse-Bias Safe Operating Area

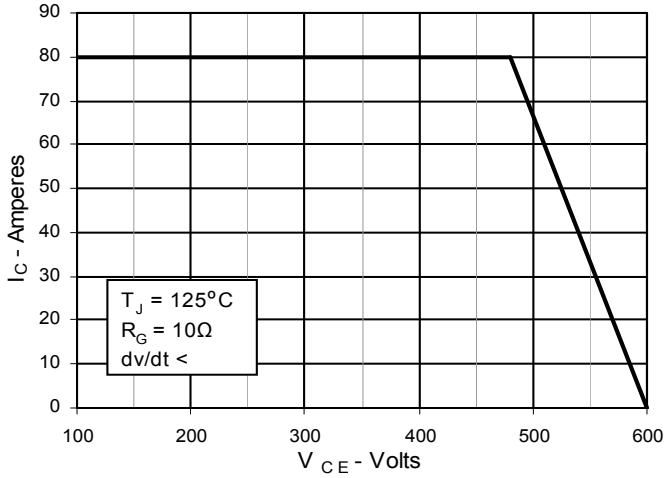


Fig. 15. Gate Charge

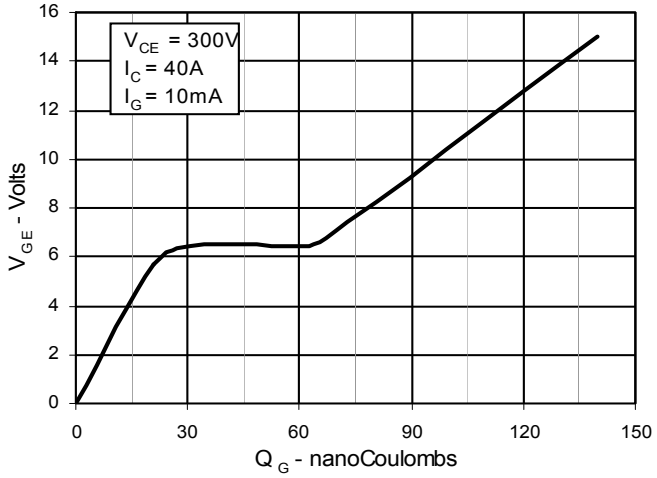


Fig. 16. Capacitance

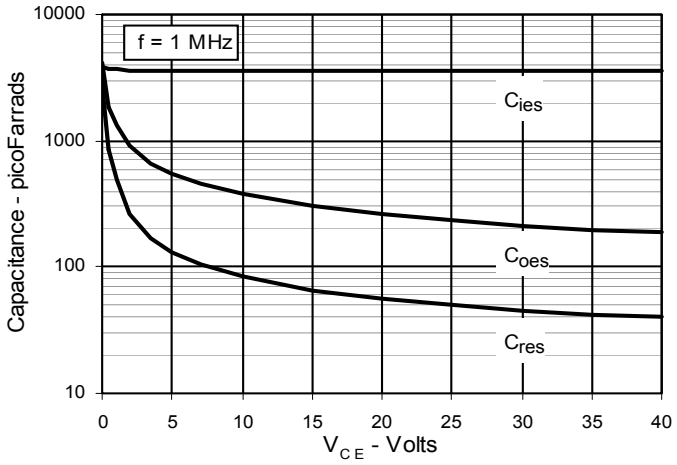
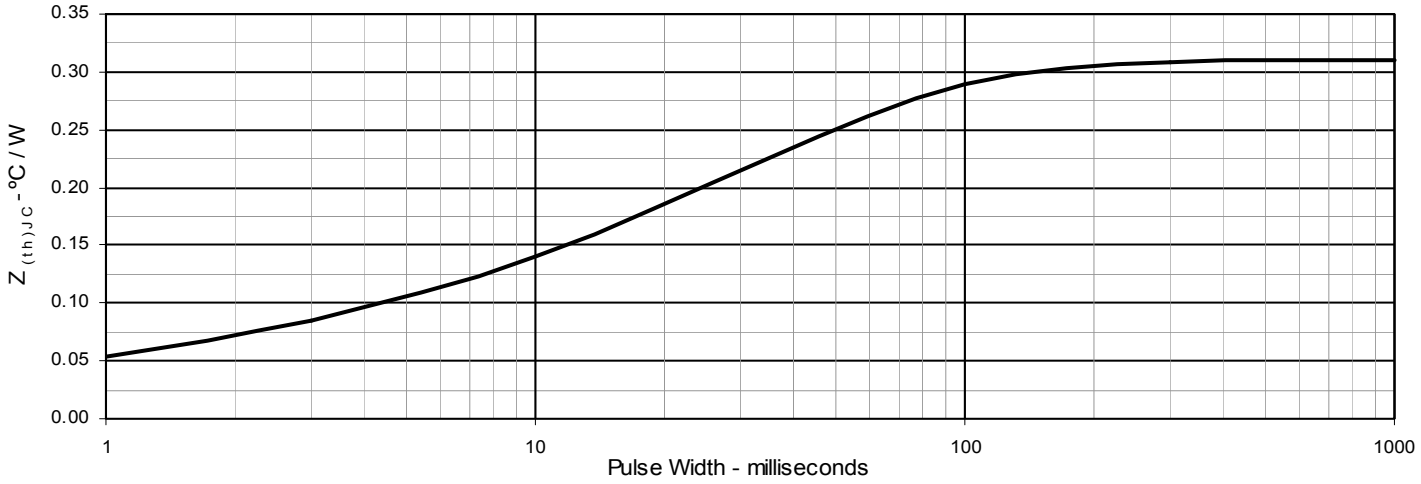


Fig. 17. Maximum Transient Thermal Resistance



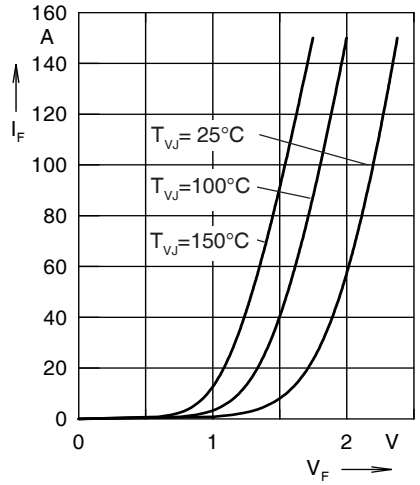


Fig. 18. Forward current I_F versus V_F

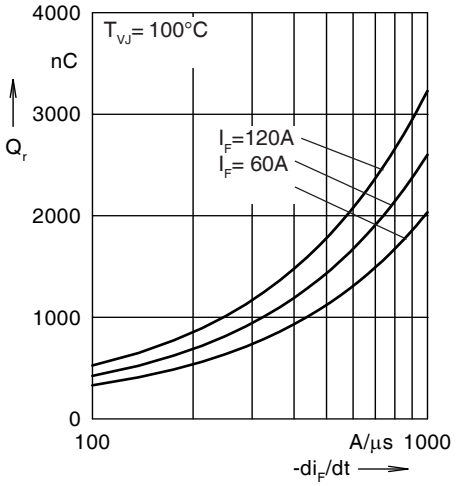


Fig. 19. Reverse recovery charge Q_r

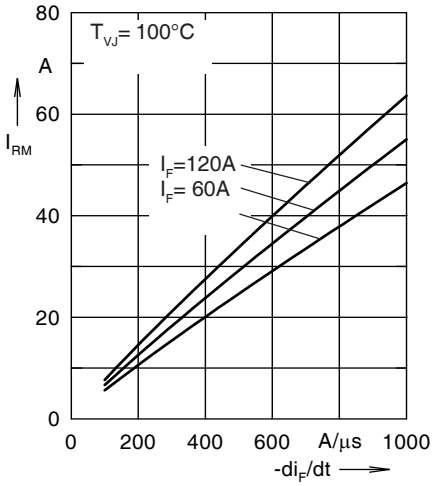


Fig. 20. Peak reverse current I_{RM}

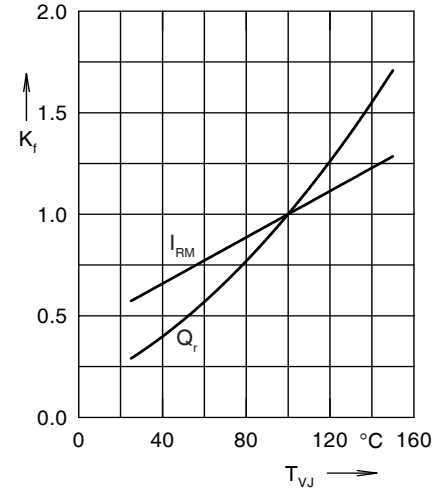


Fig. 21. Dynamic parameters Q_r, I_{RM}

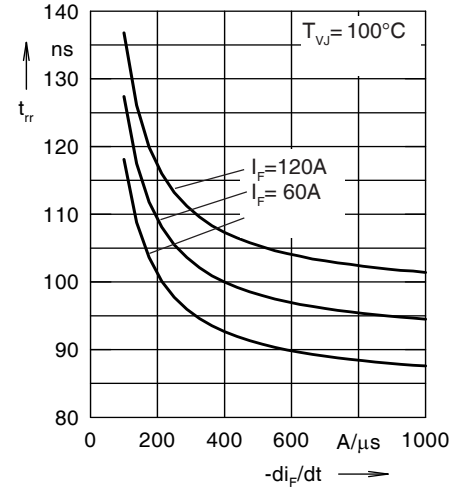


Fig. 22. Recovery time t_{rr} versus $-di_F/dt$

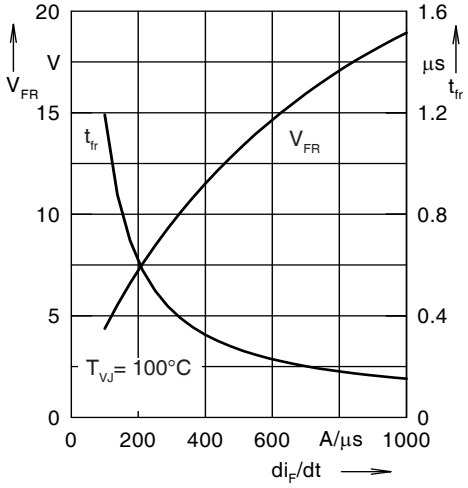


Fig. 23. Peak forward voltage V_{FR} and

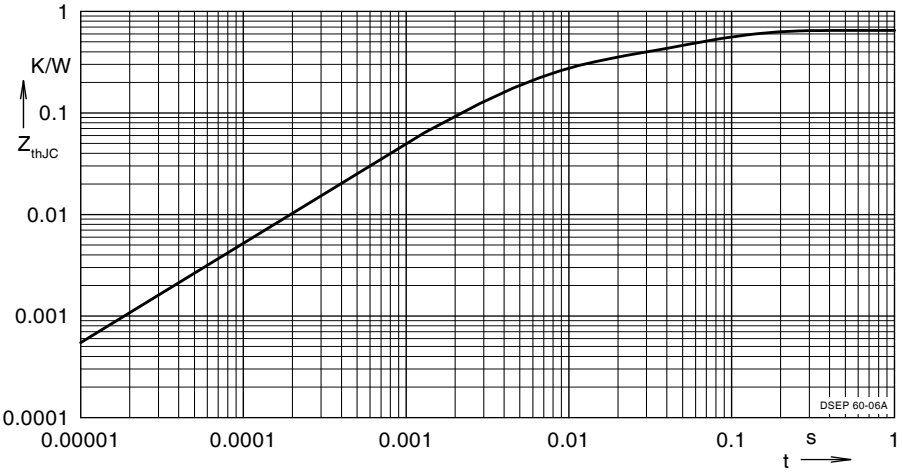


Fig. 24. Transient thermal resistance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.324	0.0052
2	0.125	0.0003

Note: Fig. 2 through Fig. 6 show typical